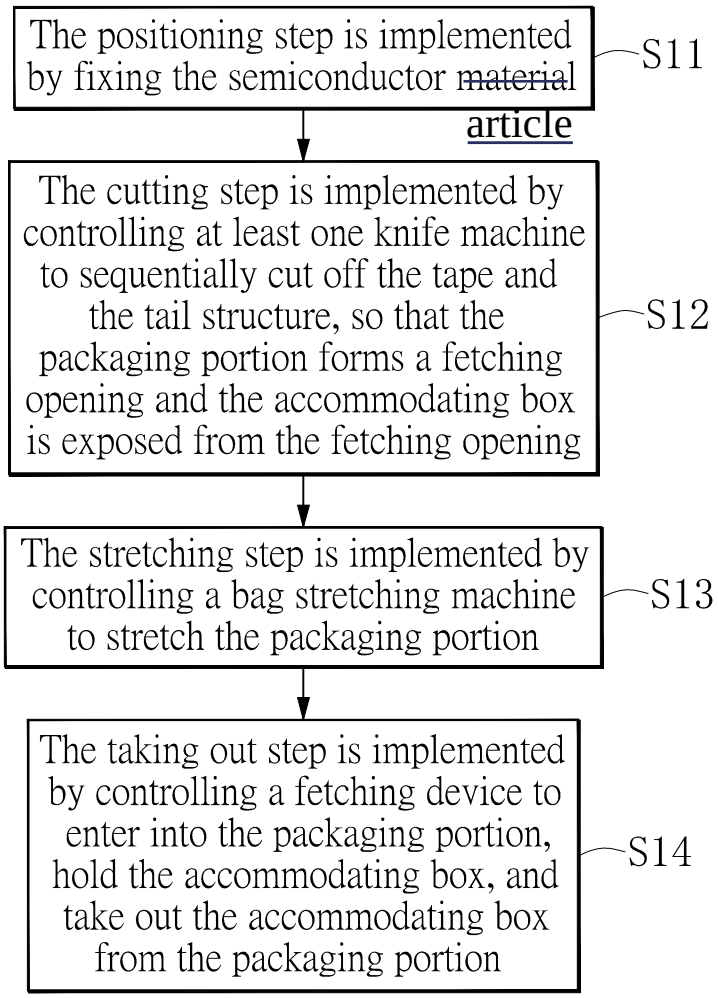

The positioning step is implemented by fixing the semiconductor ~~material~~ article
S11
The cutting step is implemented by controlling at least one knife machine to sequentially cut off the tape and the tail structure, so that the packaging portion forms a fetching opening and the accommodating box is exposed from the fetching opening
S12
The stretching step is implemented by controlling a bag stretching machine to stretch the packaging portion
S13
The taking out step is implemented by controlling a fetching device to enter into the packaging portion, hold the accommodating box, and take out the accommodating box from the packaging portion
S14

FIG. 30

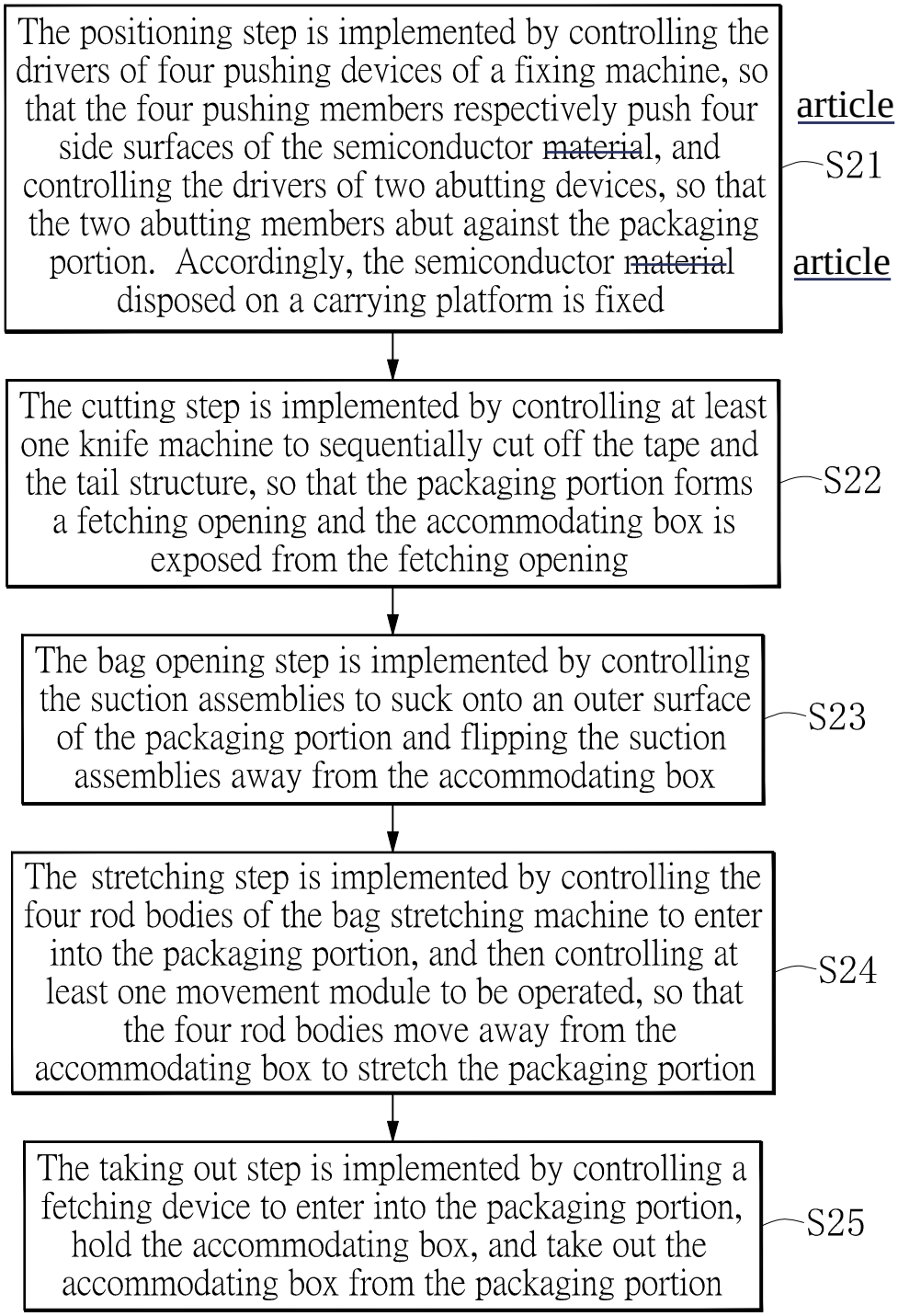

The positioning step is implemented by controlling the drivers of four pushing devices of a fixing machine, so that the four pushing members respectively push four side surfaces of the semiconductor ~~material~~, and controlling the drivers of two abutting devices, so that the two abutting members abut against the packaging portion. Accordingly, the semiconductor ~~material~~ disposed on a carrying platform is fixed
article
S21
article
The cutting step is implemented by controlling at least one knife machine to sequentially cut off the tape and the tail structure, so that the packaging portion forms a fetching opening and the accommodating box is exposed from the fetching opening
S22
The bag opening step is implemented by controlling the suction assemblies to suck onto an outer surface of the packaging portion and flipping the suction assemblies away from the accommodating box
S23
The stretching step is implemented by controlling the four rod bodies of the bag stretching machine to enter into the packaging portion, and then controlling at least one movement module to be operated, so that the four rod bodies move away from the accommodating box to stretch the packaging portion
S24
The taking out step is implemented by controlling a fetching device to enter into the packaging portion, hold the accommodating box, and take out the accommodating box from the packaging portion
S25

FIG. 31